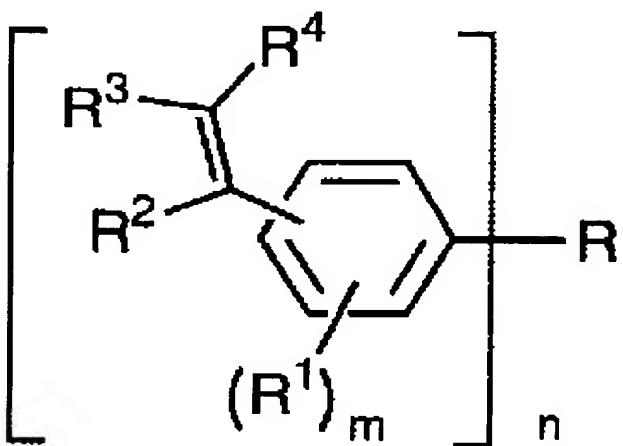


Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A resin composition comprising a crosslinking component having a weight averaged molecular weight of 1,000 or less and multifunctional styrene groups represented by the following general formula;



where R represents a hydrocarbon moiety; each R<sup>1</sup>, which may be the same or different, represents a hydrogen atom or a C<sub>1-20</sub> hydrocarbon group; R<sup>2</sup>, R<sup>3</sup> and R<sup>4</sup>, which may be the same or different, represent a hydrogen atom or a C<sub>1-6</sub> alkyl group; and m is an integer of 1 to 4, and n is an integer of 2 or more; and a rubber component having a weight averaged molecular weight of 5,000 or more and styrene units; and

the proportion of the carbon atoms and hydrogen atoms is 99% or more in said rubber component.

2. (Cancelled).

3. (Currently Amended) The resin compound according to claim-2 1, wherein said resin composition further comprises any of polyphenylene oxide, polysulfone, and polyetherimide, and polyolefin having an alicyclic structure, which may have substitutents.

4. (Currently Amended) The resin composition according to claim-2 1, wherein said resin composition further comprises, as a second crosslinking component, any of phenol resin, epoxy resin, cyanate resin, vinylbenzylether resin, and maleimide resin.

5. (Previously Presented) A curable film in which organic or inorganic cloth, unwoven cloth or film contains or is applied with the resin composition according to claim 1.

6. (Original) The curing film according to claim 5, comprising a conductive layer on at least one surface of the film.

7. (Original) A cured film wherein the curable film according to claim 6 is cured.

8. (Original) An electronic part comprising, as an insulating layer, a cured product derived from the curable film according to claim 5.

9. (Previously Presented) The resin composition according to claim 1, wherein the crosslinking component is 1,2-bis(p-vinylphenyl)ethane, the rubber component is polystyrene-block-polybutadiene, and the resin composition further comprises 2,5-dimethyl-2,5-bis(t-butylperoxy)hexyne-3 as a curing catalyst.

10. (Previously Presented) The curable film according to claim 5, wherein the crosslinking component is 1,2-bis(p-vinylphenyl)ethane, the rubber component is polystyrene-block-polybutadiene, and the resin composition further comprises 2,5-dimethyl-2,5-bis(t-butylperoxy)hexyne-3 as a curing catalyst.

11. (Previously Presented) The electronic part according to claim 8, wherein the crosslinking component is 1,2-bis(p-vinylphenyl)ethane, the rubber component is polystyrene-block-polybutadiene, and the resin composition further comprises 2,5-dimethyl-2,5-bis(t-butylperoxy)hexyne-3 as a curing catalyst.